

What is claimed is:

1. A chip for use in a voice communication device comprising:
a bone conduction sensing pattern disposed within the chip;
and
a microphone sensing pattern disposed within the chip.
2. The chip of claim 1 further comprising an integrated
circuit portion interconnected to the bone conduction sensing
pattern and the microphone sensing pattern.
3. The chip of claim 1 wherein the bone conduction sensing
pattern is positioned on a first end of the chip, the first
end opposite a second end of the chip, the microphone sensing
pattern positioned on the second end of the chip.
4. A chip for use in a voice communication device
comprising:
a substrate;
a piezoelectric polymer overlaying the substrate;
the piezoelectric polymer having a first pattern and a second
pattern, the first pattern being an accelerometer sensor
pattern and the second pattern being a microphone sensor
pattern.
5. The chip of claim 4 further comprising an electronic
sensor portion overlaying the substrate.
6. The chip of claim 5 wherein the electronic sensor
portion includes a signal conditioning circuit.

7. The chip of claim 4 wherein the piezoelectric polymer is divided into a first portion and a second portion at opposite ends of the chip, the accelerometer sensor pattern defined within the first portion and the microphone sensor pattern defined within the second portion.

8. A voice communication device comprising:
a chip having a microphone sensor and an accelerometer.

10004572, 120401